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PNP Silicon Epitaxial Transistor

This PNP Silicon Epitaxial transistor is designed for use in linear and switching applications. The device is housed in the SOT-223 package which is designed for medium power surface mount applications.

Features

- NPN Complement is PZT2222AT1
- The SOT-223 Package can be Soldered Using Wave or Reflow
- SOT-223 Package Ensures Level Mounting, Resulting in Improved Thermal Conduction, and Allows Visual Inspection of Soldered Joints. The Formed Leads Absorb Thermal Stress during Soldering Eliminating the Possibility of Damage to the Die
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-60	Vdc
Collector - Base Voltage	V _{CBO}	-60	Vdc
Emitter – Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-600	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation (Note 1) $T_A = 25^{\circ}C$	PD	1.5 12	W mW/°C
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W
Lead Temperature for Soldering, 0.0625" from case Time in Solder Bath	ΤL	260 10	°C Sec
Operating and Storage Temperature Range	T _J , T _{stg}	-65 to +150	°C

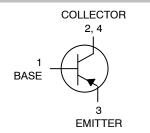
1. FR-4 with 1 oz and 713 mm² of copper area.

ON

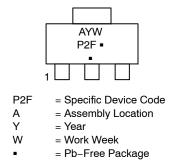
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MARKING DIAGRAM



(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]				
PZT2907AT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel				
SPZT2907AT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel				
PZT2907AT3G	SOT–223 (Pb–Free)	4,000 / Tape & Reel				

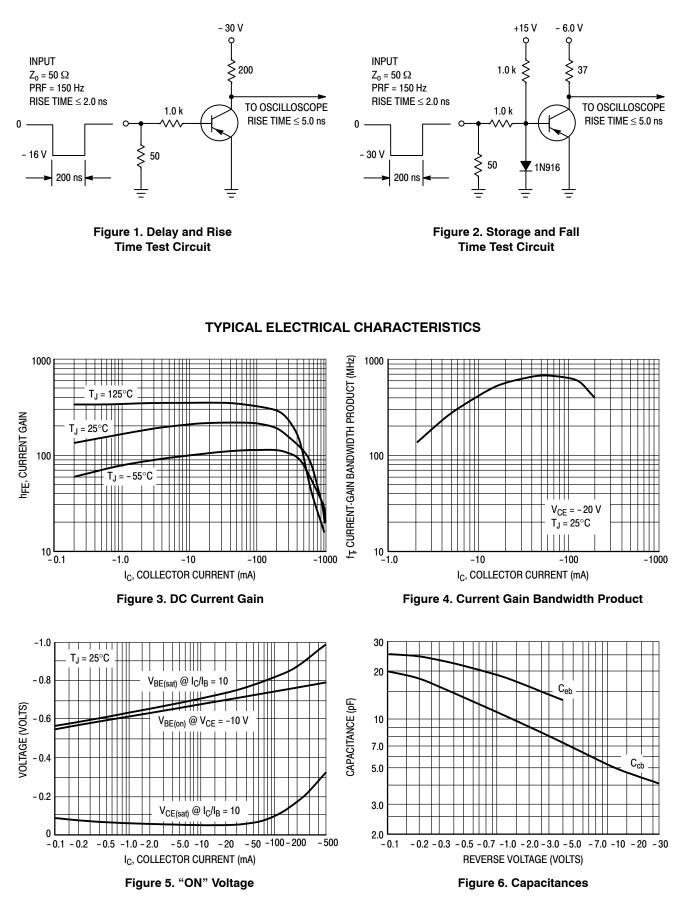
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Char	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS				•		
Collector-Base Breakdown Voltag $(I_C = -10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	-60	-	-	Vdc	
Collector-Emitter Breakdown Volta $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-60	-	-	Vdc	
Emitter-Base Breakdown Voltage $(I_E = -10 \ \mu Adc, I_C = 0)$		V _{(BR)EBO}	-5.0	_	-	Vdc
Collector–Base Cutoff Current $(V_{CB} = -50 \text{ Vdc}, I_E = 0)$		I _{CBO}	_	_	-10	nAdc
Collector–Emitter Cutoff Current ($V_{CE} = -30$ Vdc, $V_{BE} = 0.5$ Vdc))	I _{CEX}	_	_	-50	nAdc
Base-Emitter Cutoff Current (V _{CE} = -30 Vdc, V _{BE} = -0.5 Vd	I _{BEX}	_	_	-50	nAdc	
ON CHARACTERISTICS (Note	e 2)					
DC Current Gain ($I_C = -0.1 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_C = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_C = -10 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_C = -150 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$) ($I_C = -500 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}$)		h _{FE}	75 100 100 100 50	- - - - -	- - 300 -	_
Collector-Emitter Saturation Voltages ($I_C = -150 \text{ mAdc}$, $I_B = -15 \text{ mAdc}$) ($I_C = -500 \text{ mAdc}$, $I_B = -50 \text{ mAdc}$)		V _{CE(sat)}	-		-0.4 -1.6	Vdc
Base-Emitter Saturation Voltages ($I_C = -150 \text{ mAdc}$, $I_B = -15 \text{ mAdc}$) ($I_C = -500 \text{ mAdc}$, $I_B = -50 \text{ mAcc}$)	V _{BE(sat)}	-		-1.3 -2.6	Vdc	
DYNAMIC CHARACTERISTIC	cs					
Current-Gain – Bandwidth Produc (I _C = -50 mAdc, V _{CE} = -20 Vdc	f⊤	200	_	_	MHz	
Output Capacitance $(V_{CB} = -10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ M})$	C _c	-	-	8.0	pF	
Input Capacitance $(V_{EB} = -2.0 \text{ Vdc}, I_C = 0, f = 1.0$	C _e	_	-	30	pF	
SWITCHING TIMES					•	
Turn-On Time		t _{on}	-	-	45	ns
Delay Time	(V _{CC} = -30 Vdc, I _C = -150 mAdc, I _{B1} = -15 mAdc)	t _d	-	-	10	1
Rise Time		t _r	-	-	40	1
Turn-Off Time		t _{off}	-	-	100	ns
Storage Time	(V _{CC} = -6.0 Vdc, I _C = -150 mAdc, I _{B1} = I _{B2} = -15 mAdc)	t _s	-	-	80	
Fall Time		t _f	-	-	30	

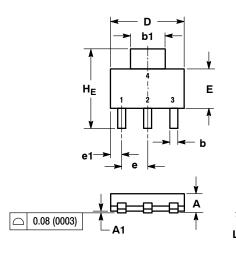
2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.



PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04

ISSUE N



NOTES

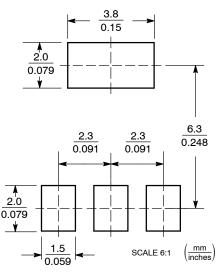
DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
Г	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4

COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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